

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5303701

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ROHIT TIRUMALA	01/16/2018
TOMMY HO	01/16/2018
FU-HO LEE	01/16/2018
MIGUEL A. SALCEDO	01/16/2018
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Name:	MICROCHIP TECHNOLOGY INCORPORATED
Street Address:	2355 W. CHANDLER BLVD.
City:	CHANDLER
State/Country:	ARIZONA
Postal Code:	85224
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16236507
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NAME OF SUBMITTER:	RYAN M. CORBETT
SIGNATURE:	/RYAN M. CORBETT/
DATE SIGNED:	12/30/2018
Total Attachments: 2	
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ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we, the below signed inventors of record, hereby assign to:

MICROCHIP TECHNOLOGY INCORPORATED
2355 WEST CHANDLER BLVD.
CHANDLER, AZ 85224-6199

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are the subject of the United States Patent Application No. 62/617,931, entitled:

"METHOD AND APPARATUS FOR REDUCING OUTPUT VOLTAGE RIPPLE IN HYSTERETIC BOOST OR BUCK-BOOST CONVERTER"

this assignment including said application, any and all United States and foreign patents, utility models, design registrations, inventor's certificates and other similar rights granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we authorize the Assignee to apply in all countries in my name, or in its own name, for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and we agree for ourselves and our heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

IN WITNESS THEREOF, we hereby set our hand, date of signature and place of signature as indicated below.

Full Name of First Inventor: Rohit Tirumala

Residence: Sunnyvale, California

Citizenship: USA

Post Office Address: 1109 Lily Ave, Sunnyvale, CA 94086



Signature of First Inventor



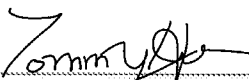
Date of Signature

Full Name of Second Inventor: Tommy Ho

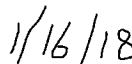
Residence: Sham Shui Po, Hong Kong

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Signature of Second Inventor



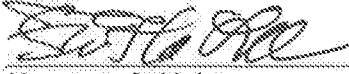
Date of Signature

Full Name of Third Inventor: Fu-Ho Lee

Residence: San Ramon, California

Citizenship: USA

Post Office Address: 109 Grassmere Circle, San Ramon, CA 94582



Signature of Third Inventor

1/16/2018

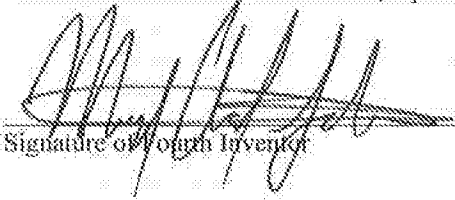
Date of Signature

Full Name of Fourth Inventor: Miguel A. Salcedo

Residence: Watsonville, California

Citizenship: Mexico

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Signature of Fourth Inventor

1/16/2018

Date of Signature